CLAIMS

[Claim 1]

A negative photosensitive resin composition comprising a cationic polymerizable compound as Component (A) and a photocationic polymerization initiator as Component (B) and at least one polymer compound selected from polyamide, polyimide, and polyamide-imide as Component (C),

wherein Component (A) contains, as Component (A1), a polyfunctional aromatic glycidyl ether having an epoxy equivalent of 80 to 145 g/eq, having a viscosity at 25 °C of 10,000 to 150,000 mPa·s and having at least two or more epoxy groups in a molecule, and

the content of Component (A1) in the total Component (A) is 60 to 80% by mass.

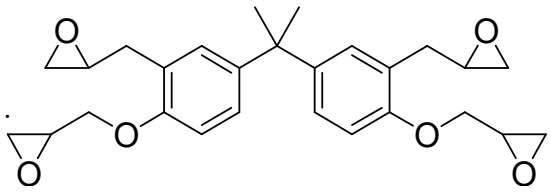
[Claim 2]

The negative photosensitive resin composition according to claim 1, wherein the content of Component (A) in the total negative photosensitive resin composition is 45 to 70% by mass.

[Claim 3]

The negative photosensitive resin composition according to claim 1, wherein Component (A1) contains a

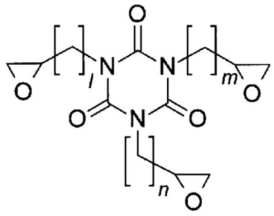
cationic polymerizable compound represented by the following general formula (A1-2):



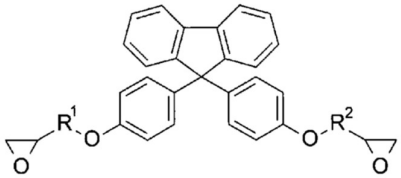
(A1-2)

[Claim 4]

The negative photosensitive resin composition according to claim 1, wherein Component (A) contains a cationic polymerizable compound selected from compounds represented by the following general formulas (1) and (2):



(1)

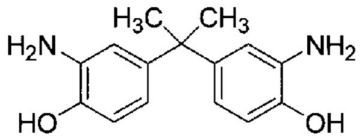


(2)

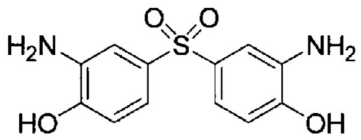
wherein, in general formula (1), l, m, and n are each independently an integer of 1 to 6; and in general formula (2), R^1 and R^2 are each independently a divalent organic group.

[Claim 5]

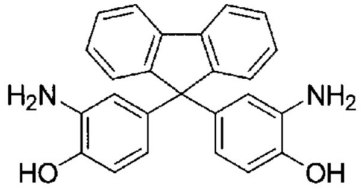
The negative photosensitive resin composition according to claim 1, wherein Component (C) contains a diamine residue derived from any of diamines of the following general formulas (3) to (7):



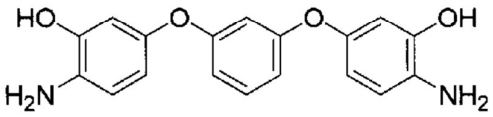
(3)



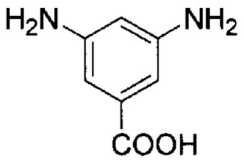
(4)



(5)



(6)



(7)

[Claim 6]

A negative photosensitive resin composition coating film comprising the negative photosensitive resin composition according to claim 1.

[Claim 7]

A negative photosensitive resin composition film comprising the negative photosensitive resin composition coating film according to claim 6 and a support.

[Claim 8]

A cured film obtained by curing the negative photosensitive resin composition according to claim 1 or the negative photosensitive resin composition coating film according to claim 6.

[Claim 9]

An electronic component comprising the cured film according to claim 8.

[Claim 10]

An electronic component comprising a structure in which two substrates are bonded via the cured film according to claim 8.